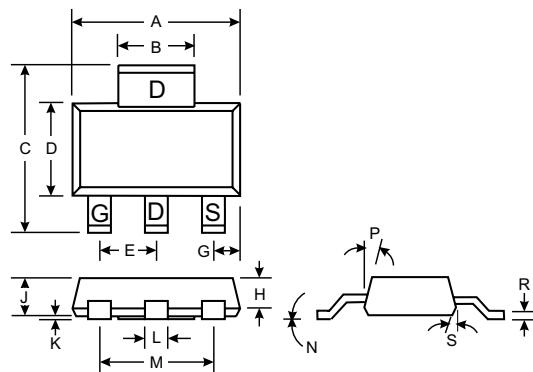


Features

- High Cell Density DMOS Technology
- Low On-State Resistance
- High Power and Current Capability
- Fast Switching Speed
- High Transient Tolerance



SOT-223		
Dim	Min	Max
A	6.30	6.71
B	2.90	3.10
C	6.71	7.29
D	3.30	3.71
E	2.22	2.35
G	0.92	1.00
H	1.10	1.30
J	1.55	1.80
K	0.025	0.102
L	0.66	0.79
M	4.55	4.70
N	—	10°
P	10°	16°
R	0.254	0.356
S	10°	16°

All Dimensions in mm

Mechanical Data

- SOT-223 Plastic Case
- Terminal Connections: See Outline Drawing and Internal Circuit Diagram Above

Maximum Ratings 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	-30	V
Gate-Source Voltage	V _{GSS}	±20	V
Drain Current Note 1a Continuous Pulsed	I _D	±3.0 ±20	A
Maximum Power Dissipation Note 1a Note 1b Note 1c	P _d	3.0 1.3 1.1	W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150	°C

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient Note 1	R _{θJA}	42	°C/W
Thermal Resistance, Junction-to-Case	R _{θJC}	12	°C/W

Notes:

1. R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.
 - a. With 1 in² oz 2 oz. copper mounting pad R_{θJA} = 42°C/W.
 - b. With 0.0066 in² oz 2 oz. copper mounting pad R_{θJA} = 95°C/W.
 - c. With 0.0123 in² oz 2 oz. copper mounting pad R_{θJA} = 110°C/W.

Electrical Characteristics 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_j = 55^{\circ}\text{C}$	I_{DSS}	—	—	1.0 10	μA	$\text{V}_{\text{DS}} = 24\text{V}, \text{V}_{\text{GS}} = 0\text{V}$
Gate-Body Leakage, Forward	I_{GSSF}	—	—	100	nA	$\text{V}_{\text{GS}} = 20\text{V}, \text{V}_{\text{DS}} = 0\text{V}$
Gate-Body Leakage, Reverse	I_{GSSR}	—	—	-100	nA	$\text{V}_{\text{GS}} = 20\text{V}, \text{V}_{\text{DS}} = 0\text{V}$
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage $T_j = 125^{\circ}\text{C}$	$\text{V}_{\text{GS(th)}}$	-1.0 -0.7	1.6 1.2	3.0 2.2	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 250\mu\text{A}$
Static Drain-Source On-Resistance $T_j = 125^{\circ}\text{C}$	$\text{R}_{\text{DS (ON)}}$	—	0.030 0.042 0.042 0.058	0.035 0.070 0.055 0.100	Ω	$\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 7.2\text{A}$ $\text{V}_{\text{GS}} = 4.5\text{V}, \text{I}_D = 6.0\text{A}$
On-State Drain Current	$\text{I}_{\text{D(ON)}}$	25 15	—	—	A	$\text{V}_{\text{GS}} = 10\text{V}, \text{V}_{\text{DS}} = 5.0\text{V}$ $\text{V}_{\text{GS}} = 4.5\text{V}, \text{V}_{\text{DS}} = 5.0\text{V}$
Forward Transconductance	g_{FS}	—	11	—	m	$\text{V}_{\text{DS}} = 10\text{V}, \text{I}_D = 7.2\text{A}$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	—	720	—	pF	$\text{V}_{\text{DS}} = 15\text{V}, \text{V}_{\text{GS}} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	370	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	250	—	pF	
SWITCHING CHARACTERISTICS (Note 2)						
Turn-On Delay Time	$t_{\text{D(ON)}}$	—	12	20	ns	$\text{V}_{\text{DD}} = 10\text{V}, \text{I}_D = 1.0\text{A}$ $\text{V}_{\text{GEN}} = 10\text{V}, \text{R}_{\text{GEN}} = 6.0\Omega$
Turn-On Rise Time	t_r	—	13	30	ns	
Turn-Off Delay Time	$t_{\text{D(OFF)}}$	—	29	50	ns	
Turn-Off Fall Time	t_f	—	10	20	ns	
Total Gate Charge	Q_g	—	19	30	nC	$\text{V}_{\text{DS}} = 10\text{V}, \text{I}_D = 3.0\text{A}$. $\text{V}_{\text{GS}} = 10\text{V}$
Gate-Source Charge	Q_{gs}	—	2.3	—	nC	
Gate-Drain Charge	Q_{gd}	—	5.5	—	nC	
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Max Continuous Drain-Source Diode Forward Current	I_s	—	—	2.3	A	
Drain-Source Diode Forward Voltage	V_{SD}	—	0.9	1.3	V	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_s = 7.2\text{A}$ (Note 2)

Notes: 2. Pulse Test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2.0\%$.

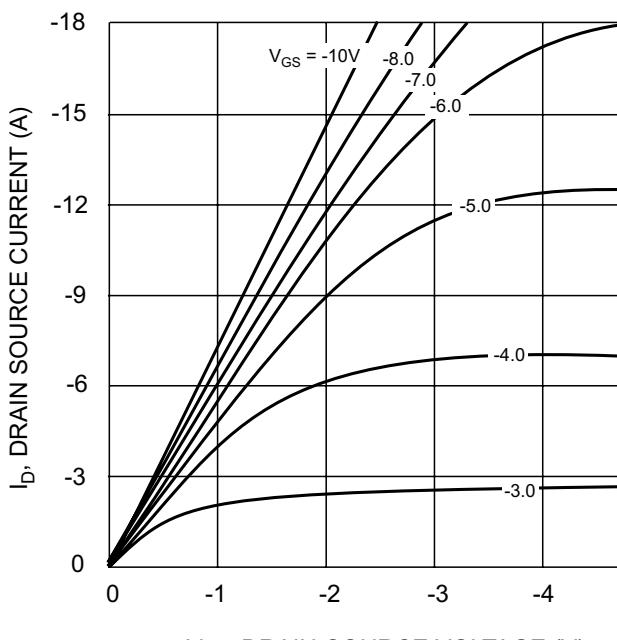


Fig. 1, On-Region Characteristics

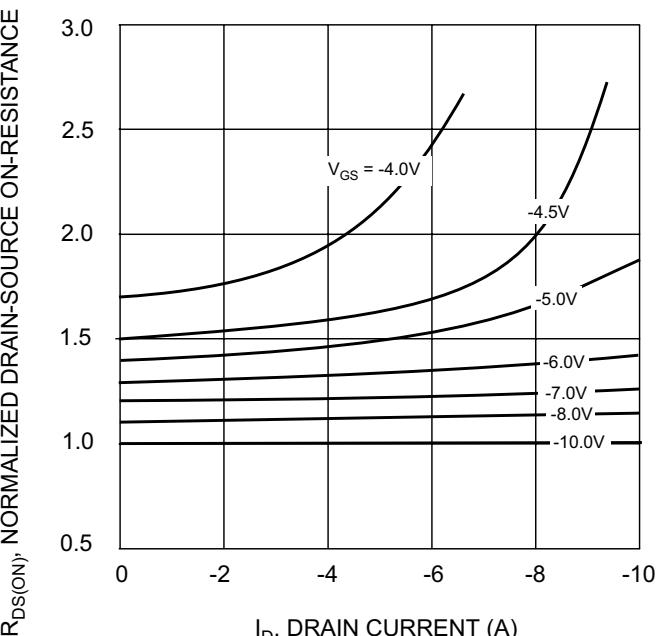


Fig. 2, On-Resistance vs Gate Voltage & Drain Current

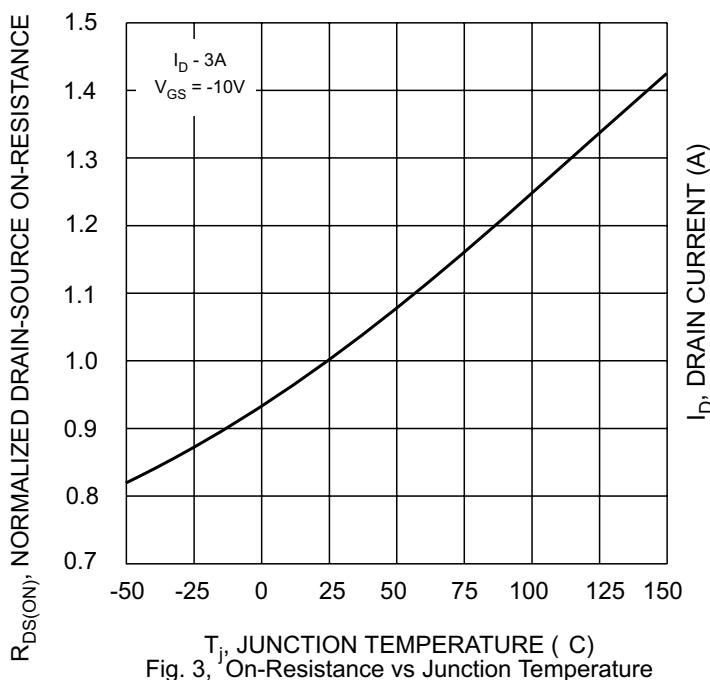


Fig. 3, On-Resistance vs Junction Temperature

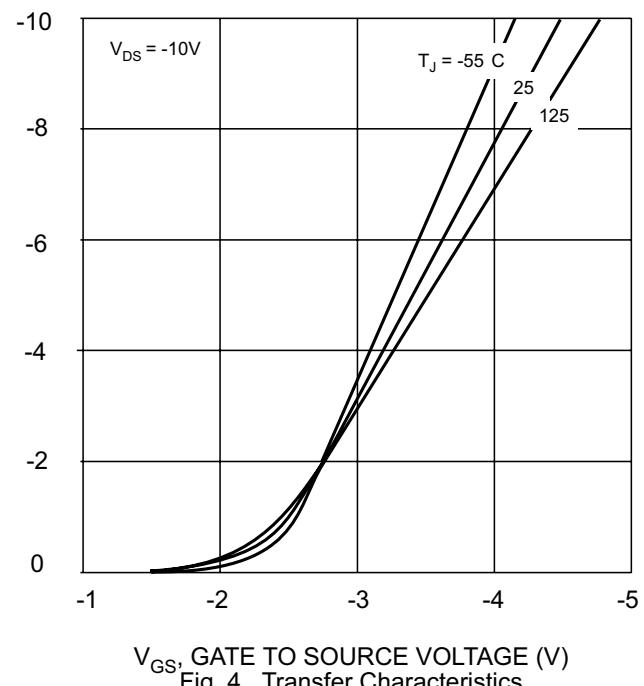
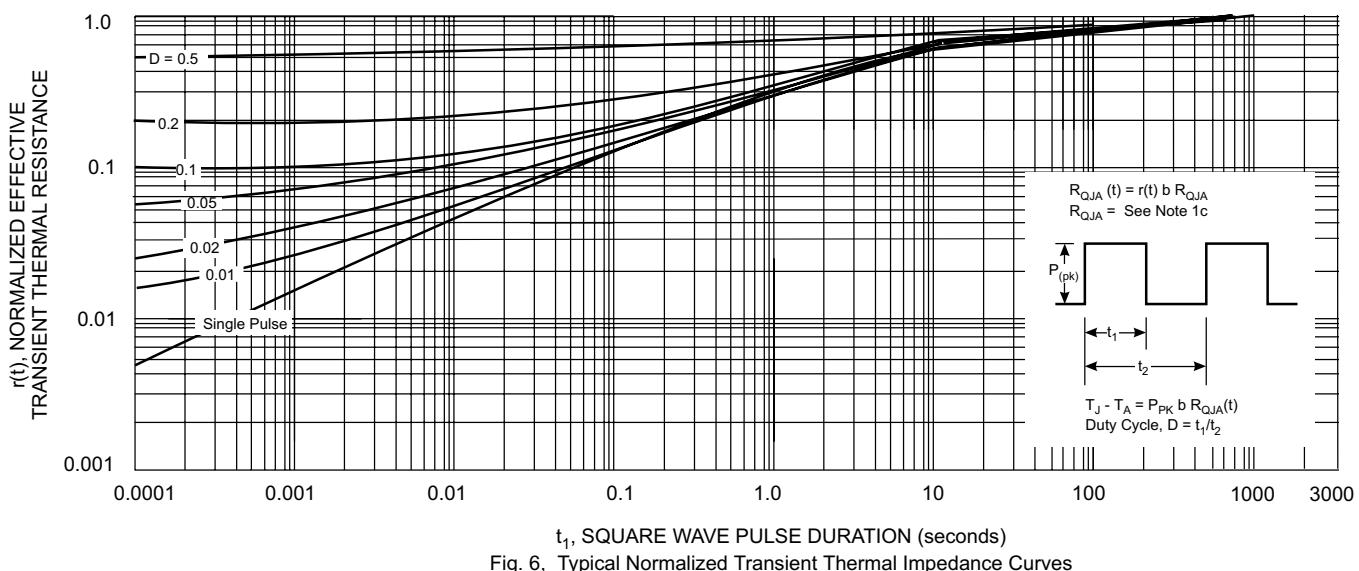
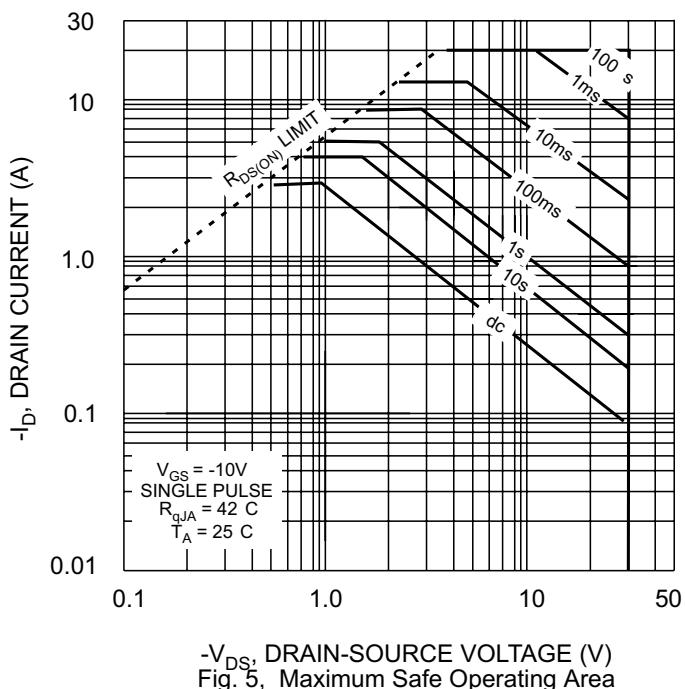


Fig. 4, Transfer Characteristics



Remark: Thermal characterization performed under conditions described in note 1c. Transient thermal response will change depending on the circuit board design.